

ABSTRACT OF THE DISCLOSURE

The present invention provides a titanium-copper alloy having high strength and excellent conductivity as a copper alloy comprising: three to four percent by mass of Ti, residual Cu, and inevitable impurities, wherein the area percentage (S(%)) of a Cu-Ti intermetallic compound phase observed in a section perpendicular to the rolling direction is represented by the following formula:

$$S(\%) \geq 8.1 \times [Ti] - 17.7$$

where [Ti] represents the Ti content in percent by mass. A method for producing the same is also provided.